

General Description

FSMOS® MOSFET is based on Oriental Semiconductor's unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially optimized for synchronous rectification systems with low driving voltage.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switched mode power supply

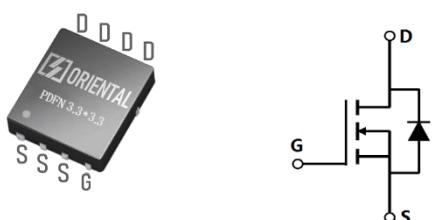
Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	60	V
$I_D, pulse$	180	A
$R_{DS(ON), max} @ V_{GS}=10V$	4.5	mΩ
Q_g	31.3	nC

Marking Information

Product Name	Package	Marking
SFS06R045UNF	PDFN3.3*3.3	SFS06R045UN

Package & Pin information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	60	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	60	A
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D,\text{pulse}}$	180	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	60	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S,\text{pulse}}$	180	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	31	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	49	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	4.03	$^\circ\text{C}/\text{W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	60			V	$V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.3		2.4	V	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		3.7	4.5	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=20 \text{ A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		5.3	6.5	$\text{m}\Omega$	$V_{GS}=4.5 \text{ V}, I_D=20 \text{ A}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20 \text{ V}$
Gate-source leakage current	I_{GSS}			-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=60 \text{ V}, V_{GS}=0 \text{ V}$
Gate resistance	R_G		2.9		Ω	$f=1 \text{ MHz}, \text{Open drain}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		2110		pF	V _{GS} =0 V, V _{DS} =25 V, f=100 kHz
Output capacitance	C _{oss}		604		pF	
Reverse transfer capacitance	C _{rss}		50.6		pF	
Turn-on delay time	t _{d(on)}		19.2		ns	V _{GS} =10 V, V _{DS} =30 V, R _G =2 Ω, I _D =60 A
Rise time	t _r		6.2		ns	
Turn-off delay time	t _{d(off)}		43.2		ns	
Fall time	t _f		8.6		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		31.3		nC	V _{GS} =10 V, V _{DS} =30 V, I _D =60 A
Gate-source charge	Q _{gs}		6.2		nC	
Gate-drain charge	Q _{gd}		5.9		nC	
Gate plateau voltage	V _{plateau}		3.6		V	

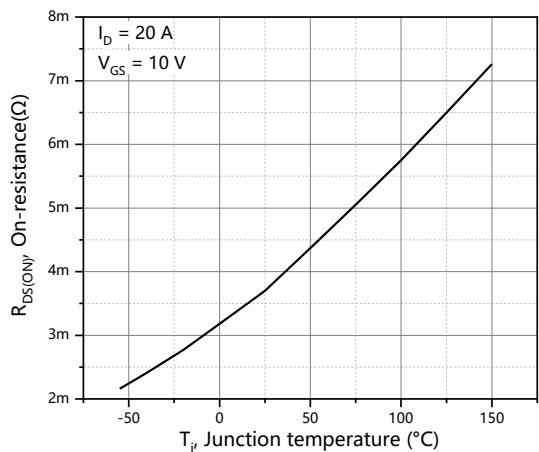
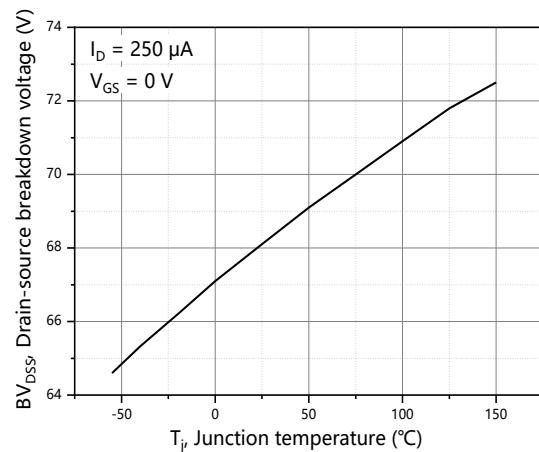
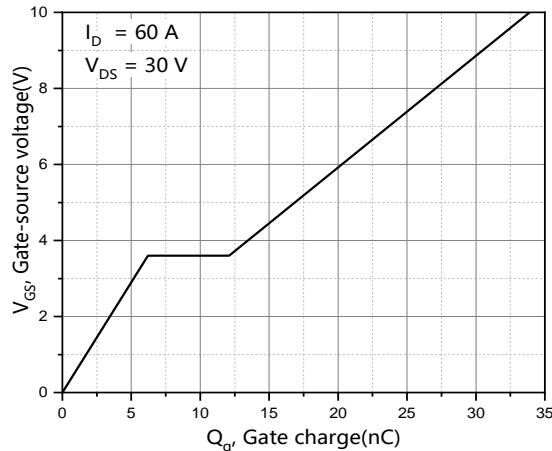
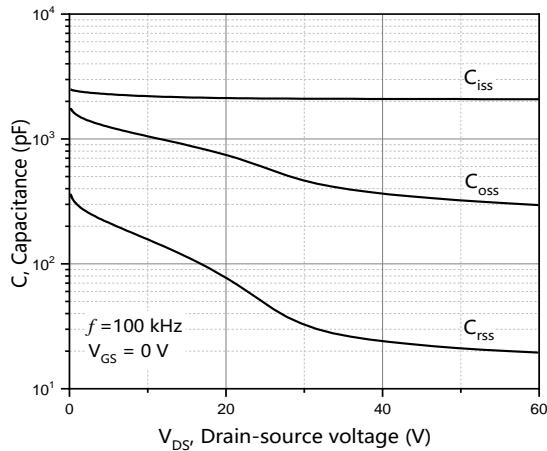
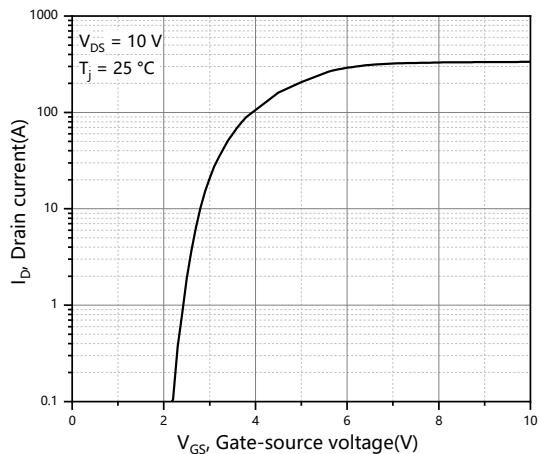
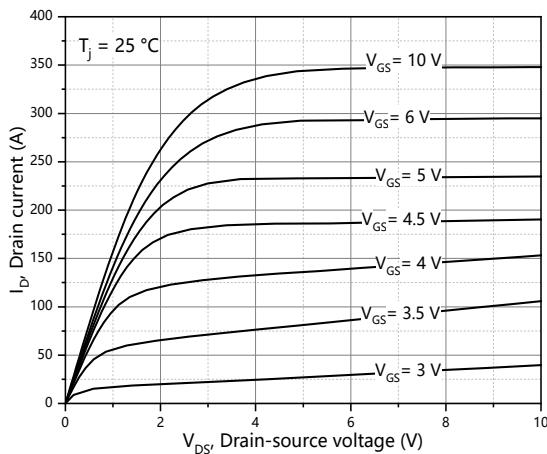
Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =20 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		61.2		ns	V _R =48 V, I _S =50 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		35		nC	
Peak reverse recovery current	I _{rrm}		1		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=50 V, V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams



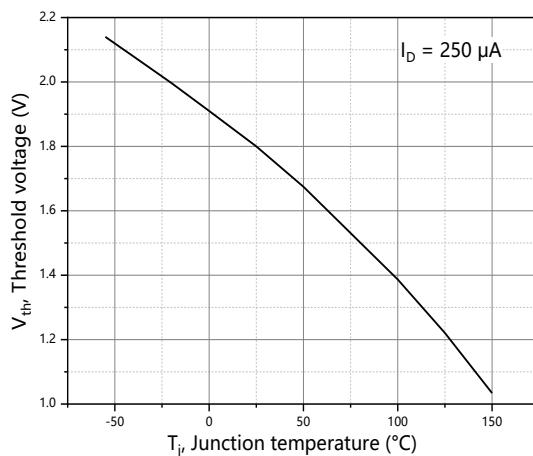


Figure 7. Threshold voltage

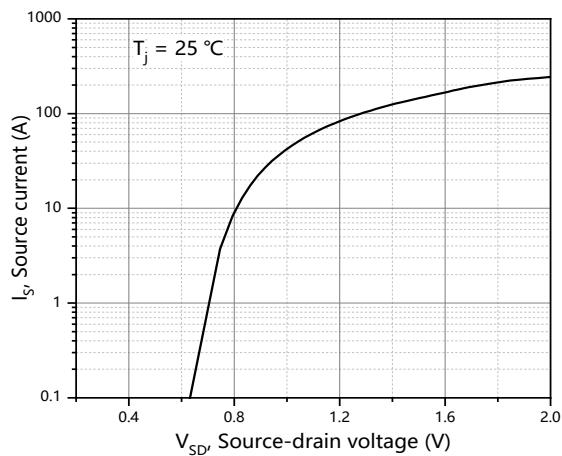


Figure 8. Forward characteristic of body diode

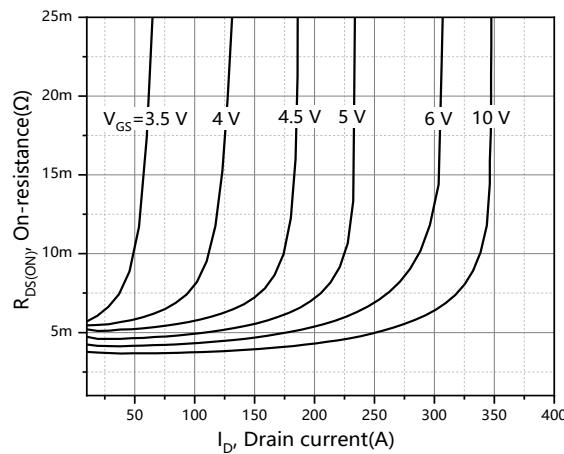


Figure 9. Drain-source on-state resistance

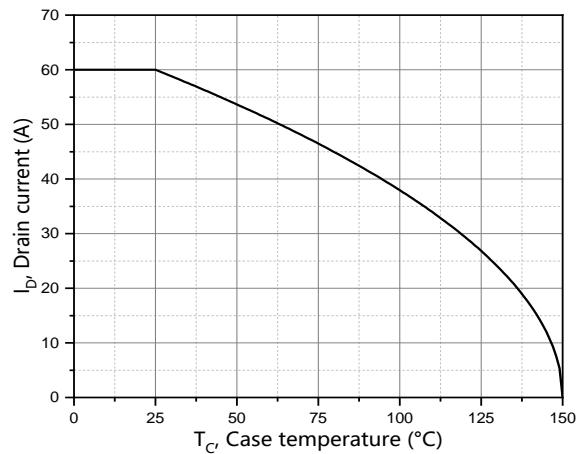


Figure 10. Drain current

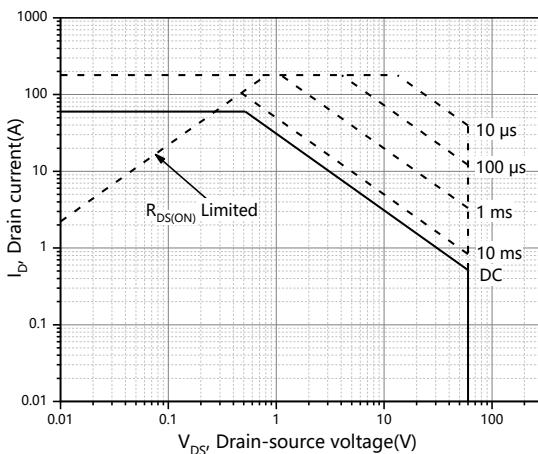


Figure 11. Safe operation area $T_C=25\text{ }^{\circ}\text{C}$

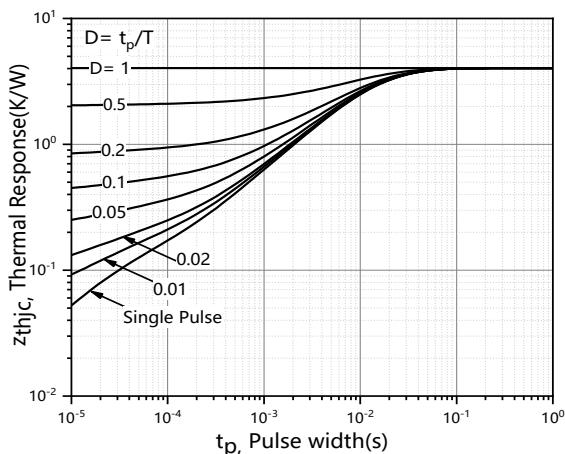


Figure 12. Max. transient thermal impedance

Test circuits and waveforms

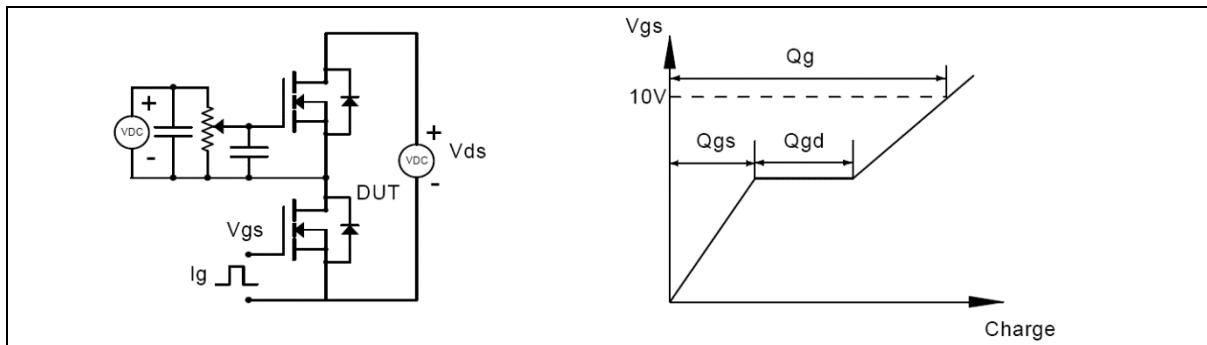


Figure 1. Gate charge test circuit & waveform



Figure 2. Switching time test circuit & waveforms



Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

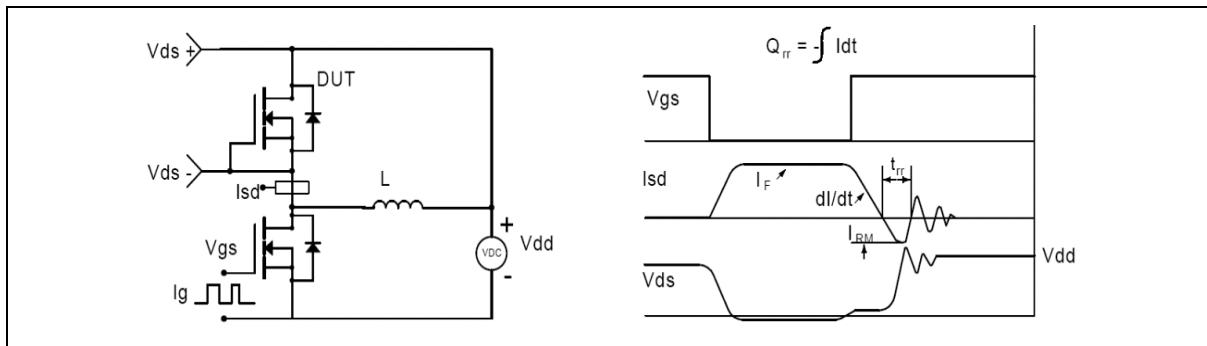
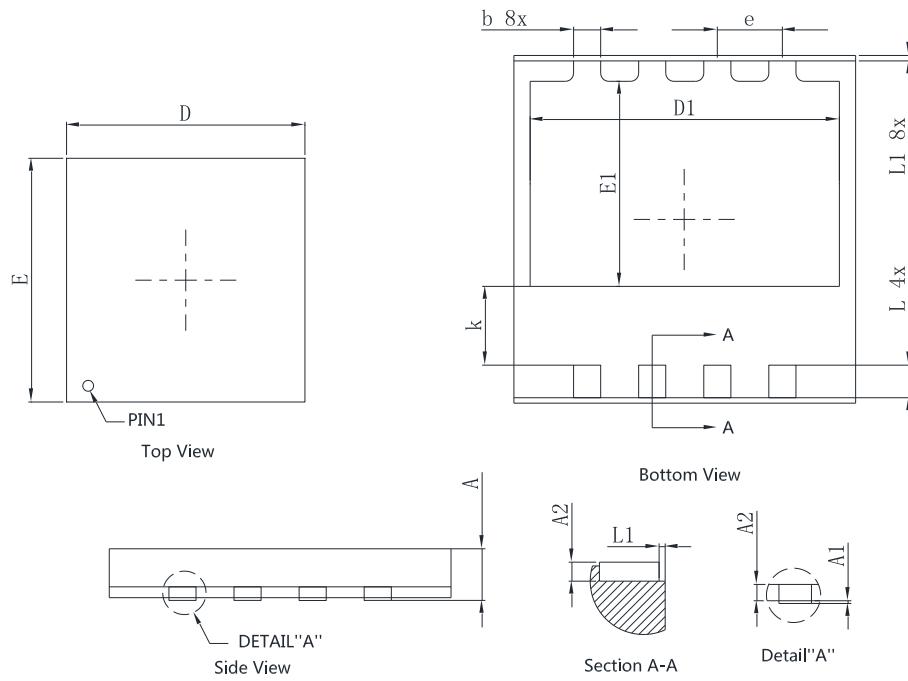


Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	0.50	-	0.60
A1	-	-	0.005
A2	0.10	-	0.25
D	3.20	3.30	3.40
E	3.20	3.30	3.40
D1	2.80	2.90	3.00
E1	1.91	2.01	2.11
b	0.25	0.30	0.35
L	0.30	0.35	0.40
L1	0.01	0.05	0.09
k	0.57	0.67	0.77
e	0.65 BSC		

Version 1: PDFN3.3*3.3-X package outline dimension

Ordering Information

Package Type	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
PDFN3.3*3.3-X	5000	1	5000	8	40000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFS06R045UNF	PDFN3.3*3.3	yes	yes	yes

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